

**AMENDMENTS TO THE CLAIMS:**

*This listing of claims will replace all prior versions, and listings, of claims in the application:*

1-7. (Canceled)

8. (Currently amended) A method of manufacturing a silicon wafer, the method comprising the following steps in the order recited:

polishing side faces of a silicon block used for manufacturing the silicon wafer; and  
slicing the silicon block, so that said slicing is performed after said polishing.

9. (Previously presented) The method of claim 8, wherein the polished side faces of the silicon block have a surface roughness  $R_y$  of  $8\mu\text{m}$  or less.

10-11. (Canceled)

12. (New) A silicon wafer processing method, comprising:  
slicing a silicon block having a rectangle or almost rectangle section into silicon wafers,  
wherein the silicon block is sliced after a side face of the silicon block to serve as  
circumferential faces of the silicon wafers is polished.

13. (New) The method of claim 12, wherein the silicon block is a rectangular and/or square block obtained by cutting a silicon ingot.

14. (New) A method of making a silicon wafer, comprising the following steps in the order recited:

    chamfering edges of a silicon block used for manufacturing the silicon wafer,  
    mechanically polishing side faces of the silicon block to serve as a circumferential face of the silicon wafer, and  
    slicing the silicon block.

15. (New) The method of claim 14, wherein the silicon block is obtained by cutting a silicon ingot.